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Shiau et al.

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[54] **METHOD OF PROVIDING UNIFORM PHOTORESIST COATINGS FOR TIGHT CONTROL OF IMAGE DIMENSIONS**

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[52] **U.S. Cl.** **427/240**; 427/314; 427/407.1; 427/337; 427/384; 438/761; 438/782

[58] **Field of Search** 427/240, 314, 427/372.2, 407.1, 337, 384; 438/761, 782

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[57] **ABSTRACT**

A method for providing a uniform coating of photoresist over substrate for defining high density integrated device and circuit patterns. This is accomplished by applying the photoresist onto the substrate in multiple, separate dispensing steps and leveling spins to attain the designed thickness uniformly over substrate having high topographic surfaces, thereby preserve the integrity of the critical dimension for multi-level alignments used in the fabrication of integrated devices and circuits.

21 Claims, 3 Drawing Sheets

